



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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ATTY.'S DOCKET: 98 P 7501 US 01

Do Not Enter 8/6/03

re the application of:)
Ramachandran et al.) Group Art: 1746
Serial No.: 09/204,706)
Examiner: A. Olsen
Filing Date: December 3, 1998)
Title: REMOVAL OF POST-RIE POLYMER)
ON Al/Cu METAL LINE)

AMENDMENT UNDER 37 C.F.R. §1.116

Commissioner For Patents
P.O. Box 1450
Arlington, VA 22313-1450

Sir:

Responsive to the Office Action of September 10, 2002,
please amend the application as follows:

IN THE CLAIMS:

13. (5th Amendment) In a metal etch tool for removing post-RIE polymer rails formed on a Al/Cu metal line of a semiconductor structure, the improvement comprising:

[I] an integrated metal etch tool interfaceable with:

a) strip chamber means [for water only plasma] to strip photo-resist of a semiconductor composite structure subsequent to a RIE to limit thickness of sidewall polymer rails;

b) vacuum chamber means to chemically modify sidewall polymer rails [by supplying a mixture of an etching gas/acid neutralizing gas of HF/NH₃] to form a water soluble residue material of sidewall polymer rails left behind on [the] a Al/Cu metal line from the RIE process; and

c) deionized water rinse chamber means to [remove] rinse [water] soluble material.

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OFFICE OF PETITIONS